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March 2008

JOINT INDUSTRY STANDARD

Moisture/Reflow Sensitivity Classification for Nonhermetic Surface Mount Devices



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Moisture/Reflow Sensitivity Classification for Nonhermetic Surface Mount Devices

A joint standard developed by the IPC Plastic Chip Carrier Cracking Task Group (B-10a) and the JEDEC JC-14.1 Committee on Reliability Test Methods for Packaged Devices

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Users of this standard are encouraged to participate in the development of future revisions.

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Any document involving a complex technology draws material from a vast number of sources across many continents. While the principal members of the Joint Moisture Classification Working Group are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC and JEDEC extend their gratitude.

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In Memorium

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